

GLOSSARY

This glossary contains explanations of certain technical terms used in this document in connection with us and our business. As such, some of these terms and their meanings may not correspond to standard industry definitions or usage of these terms and may not be comparable to similar terms adopted by other companies.

“acrylate”	the esters, salts and conjugate bases of acrylic acid with its derivatives
“acoustic enhancement materials”	specialized, innovative materials specifically applied to consumer electronic smart terminals such as smartphones, tablets, laptops, smart wearables and AI glasses/XR devices, designed to enhance, control, or achieve better acoustic performance
“advanced packaging”	technologies that integrate multiple semiconductor advanced processes that integrate multiple chips and components into a single unit, overcoming limitations of traditional packaging to lower power consumption and smaller sizes
“AI”	artificial intelligence
“AI glasses”	wearable devices that incorporate advanced computer vision, augmented reality and artificial intelligence technologies to enhance the user’s visual experience, providing real-time information, interactive overlays and intelligent assistance for a wide range of applications, from navigation and visualization to accessibility and entertainment
“alumina powder”	an aluminum oxide powder material produced through multiple processes such as grinding, precision classification, and impurity removal
“CCL”	copper clad laminate, the fundamental material for making Printed Circuit Boards (PCBs), consisting of thin copper foil bonded to a non-conductive substrate like fiberglass, soaked in resin (like epoxy), forming a rigid board used to create electronic circuits and offering electrical insulation with conductive copper pathways
“cell”	the smallest battery unit
“CMP”	chemical mechanical polishing, an advanced semiconductor manufacturing process that combines chemical reactions and mechanical abrasion to planarize and smooth the surface of wafers

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“CMP powder”	chemical mechanical polishing powder, refers to the nano-sized abrasive particles (such as silica, alumina or ceria) suspended in a liquid slurry, used with chemicals to achieve smooth, flat surfaces on materials like silicon wafers by combining chemical softening and mechanical abrasion
“coating”	a method for preparing composite films by coating polymer paste, molten polymer, or polymer solution incorporated with ceramic powder onto a film substrate
“computing power”	the overall capacity of a system to process data and execute complex calculations, fundamental to running advanced applications in AI, data analytics, and immersive technologies
“electronic adhesives”	precision adhesives specifically applied to electronic and electrical products, which can achieve specific functions such as bonding, sealing, securing, thermal conduction, electrical conduction, insulation and protection
“electronic ceramic materials”	functional inorganic ceramics with tailored dielectric, insulating, piezoelectric and thermal properties, primarily used for manufacturing electronic ceramic components, precision ceramic structural parts, semiconductor packaging products, lithium-ion battery separator coating, etc.
“electronic ceramic powder”	specially formulated and processed inorganic non-metallic fine powder, being a form of electronic ceramic materials, used for manufacturing electronic ceramic components, precision ceramic structural parts, cathode material additives, lithium-ion battery separator coating, etc.
“electronic functional enhancement materials”	materials designed to enhance the specific physical (including acoustics, heat dissipation/thermal conductivity, optics, electrical conductivity, electromagnetism, and other) or chemical properties of electronic devices, components, and electrical systems
“EMC”	epoxy Molding Compound, a thermosetting composite material, typically a solid powder pellet, made of epoxy resins, hardeners, silica fillers, and additives, used to encapsulate and protect sensitive electronic components (like chips) during manufacturing, providing crucial resistance to moisture, heat, chemicals and mechanical shock
“energy enhancement materials”	a category of functional auxiliary materials designed to improve energy conversion efficiency and product performance, mainly comprising PV back-glass coating materials, PV conductive paste, PV cell additives, etc., which are widely applied in photovoltaic and other new energy sectors

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“epoxy”	polymer oligomer whose molecular structure contains two or more epoxy groups, and its backbone is usually composed of organic compounds such as aliphatic, alicyclic or aromatic compounds. It undergoes cross-linking reactions with various curing agents through the epoxy groups to form useful thermosetting products
“high-purity nano-alumina”	aluminum oxide (Al_2O_3) powder of approximately 99.995% purity (4N+) with primary particles of 100 to 300 nm. Produced through wet-chemical routes, it combines controlled trace impurities with high sintering activity, enabling low-temperature densification for high-end ceramic substrates, semiconductor ceramic components and CMP slurries
“inorganic non-metallic materials”	a class of materials composed of oxides, carbides, nitrides, halides, borides, as well as silicates, aluminates, phosphates, borates, and other substances, and it serves as the general term for all materials excluding organic polymer materials and metallic materials
“kg”	kilogram, the SI unit basis of mass, defined as one thousand grams
“LMC”	liquid molding compound, a flowable polymer resin mixed with fillers and curing agents, used to encapsulate and protect electronic components or form complex plastic parts by pouring into a mold where it cures into a solid, offering precise coverage, excellent insulation and enhanced device reliability
“lithium-ion battery” or “LIB”	batteries that utilize lithium-ions as conductive ions that move between the anode and cathode, and charge and discharge through the mutual conversion of chemical energy and electrical energy
“LIB separator coating materials”	functional materials coated on the surface of lithium-ion battery separators via precision coating technology
“microphone”	Electronic device that collects audio signals and transmits or converts them into digital signals for electronic products for the purposes of voice recording, voice recognition, amplifying or enabling voice command functions
“modules”	packaged components that are applied in optical, acoustic and photovoltaic fields, or serve as other electronic components, which are used to build larger systems or devices. They are essential for enhancing performance, efficiency, and scalability in electronic products
“N’BASS Materials”	N’BASS acoustic enhancement material, a type of powder designed to create a virtual back-cavity effect and improve low-frequency acoustic performance

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“NPI”	new product introduction, a process which includes all activities undertaken within an organization to define, develop and market a new or improved product or solution
“PCB”	printed circuit board, a flat board made of insulating material, typically fiberglass or composite epoxy, with conductive pathways etched from copper sheets
“photovoltaic” or “PV”	the conversion of light into electricity using semiconducting materials that exhibit photovoltaic effect
“PV back-glass coating materials”	special coating materials applied to the surface of PV back glass to improve the power of photovoltaic modules
“R&D”	research and development
“ROIC”	return on invested capital, a key profitability metric showing how well a company generates profits from the capital invested in it
“separator”	a permeable membrane placed between a battery’s anode and cathode, keeping the two electrodes apart to prevent electrical short circuits while also allowing the transport of ionic charge carriers needed to close the circuit during the passage of current in an electrochemical cell
“sound-adsorbing particles”	porous ceramic materials, primarily including N’BASS Materials, which are specially designed to form a virtual back cavity to improve acoustic performance
“PV conductive paste”	a viscous paste that is a mechanical mixture composed of high-purity (99%) metallic silver micro-particles, binders, solvents, and additives
“thermal conductivity”	the measure of a material’s ability to conduct heat, or the rate at which heat is transferred through a material per unit area and temperature gradient
“underfill”	underfill adhesives, mainly applied via non-contact jetting dispensing, can effectively reduce the impact between the silicon chip and the substrate during the underfill process of chip-scale packaging (CSP) and ball grid array (BGA), thereby effectively improving product durability
“UV”	ultraviolet light, an electromagnetic radiation with a wavelength ranging from 10 nm to 400 nm, shorter than visible light but longer than X-rays

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“virtual expansion coefficient”	virtual rear cavity expansion coefficient, a core quantitative indicator for measuring the capability of N’BASS Materials to amplify the equivalent acoustic volume of the rear cavity of a microspeaker, without changing the physical size of the cavity. It equals to equivalent acoustic rear cavity volume divided by actual physical rear cavity volume
“VOC”	volatile organic compounds, refer to any organic liquids or solids that can volatilize and pose hazards under normal temperature and pressure
“wafer”	a thin slice of semiconductor material, typically crystalline silicon, which serves as a substrate to build electrical circuits through complicated wafer fabrication processes
“XR”	extended reality, encompassing immersive technologies, including virtual reality, augmented reality and mixed reality, that use computer-generated content to enhance, overlay or replace a user’s perception of the physical world and/or enable interaction between digital content and the physical environment
“μm”	micrometer, a metric unit of linear measure that equals one-millionth of a meter